



# 256k SRAM Interlevel Shorts

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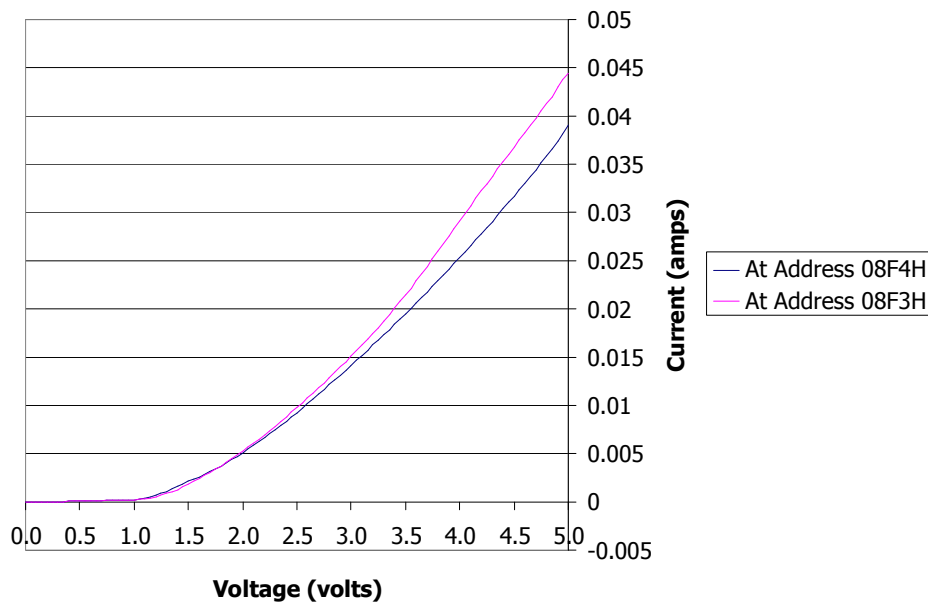
Sandia is a multiprogram laboratory operated by Sandia Corporation, a Lockheed Martin Company,  
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under contract DE-AC04-94AL85000.

# Background Information

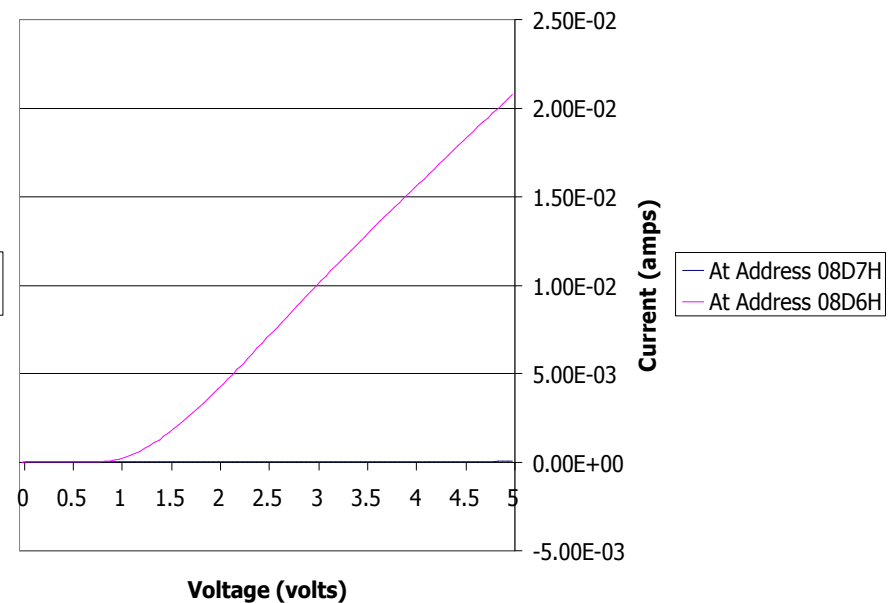
- ICs failed electrical test after packaging
  - ~ 10% fallout (9 of 89)
  - Extract same vectors sets used before and after packaging
- Indication of column failures from the test data
- ICs packaged in 28 pin CERDIPs with metal lids

# I-V Characterization

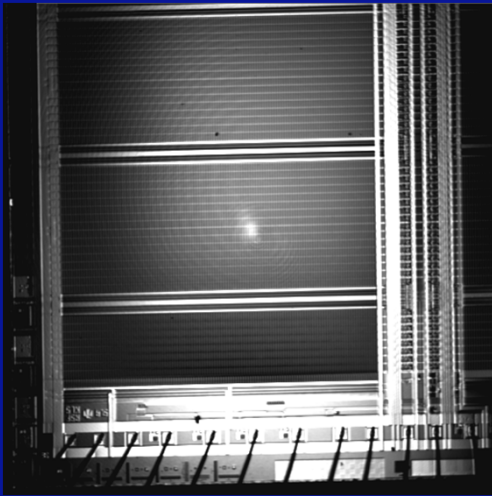
I-V Characteristics for SA3921 SN1674



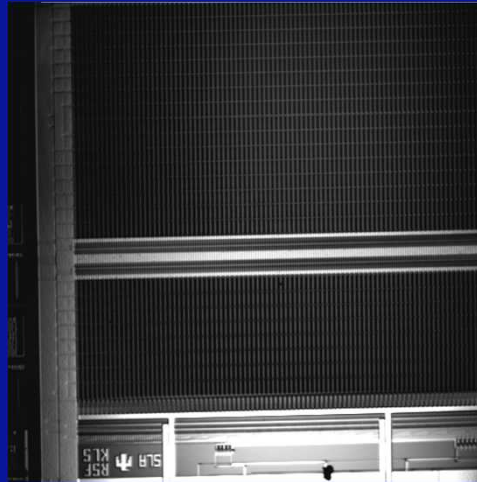
I-V Characteristics for SA3921 SN1684



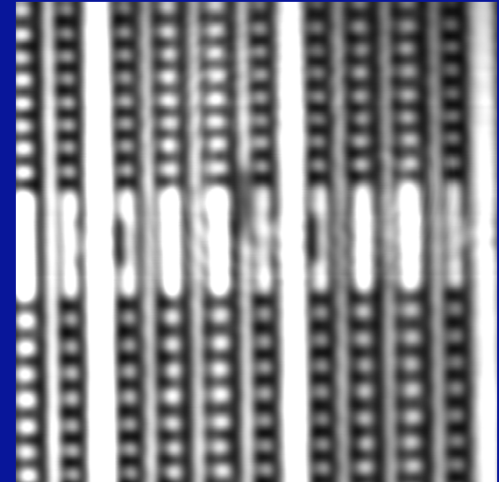
# IR Optical & TIVA Images of SN 1669



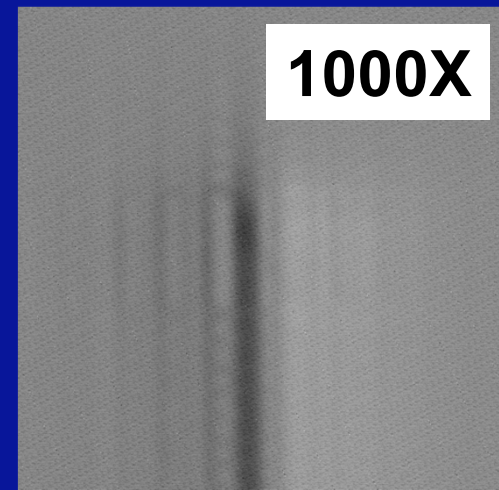
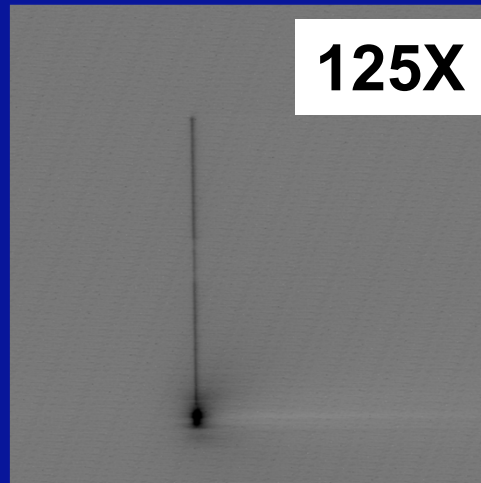
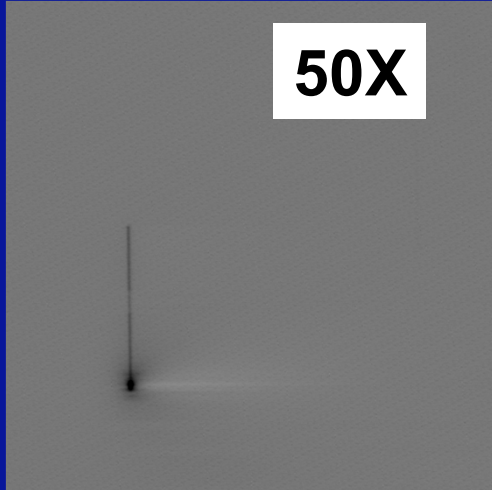
**50X**



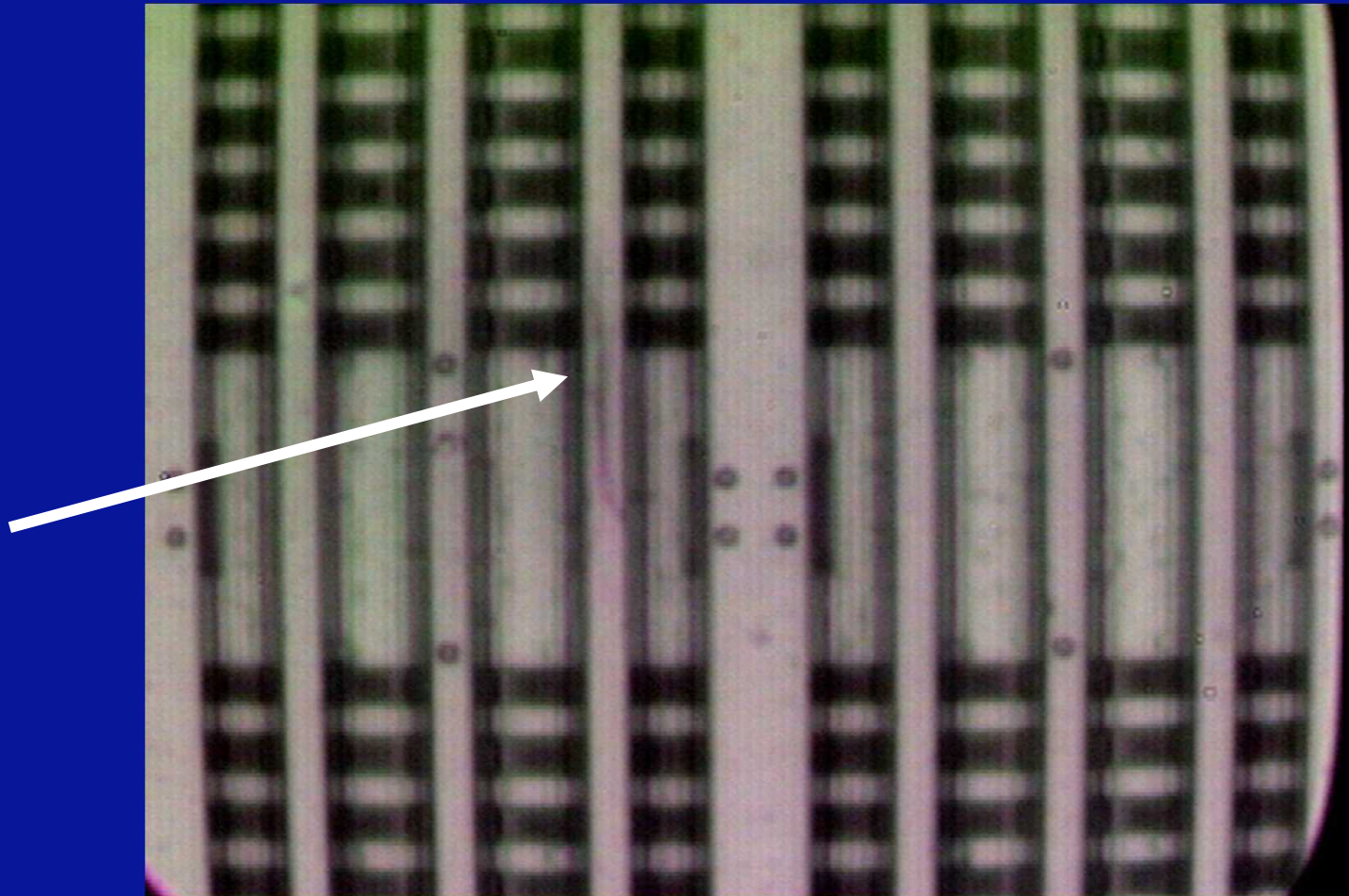
**125X**



**1000X**

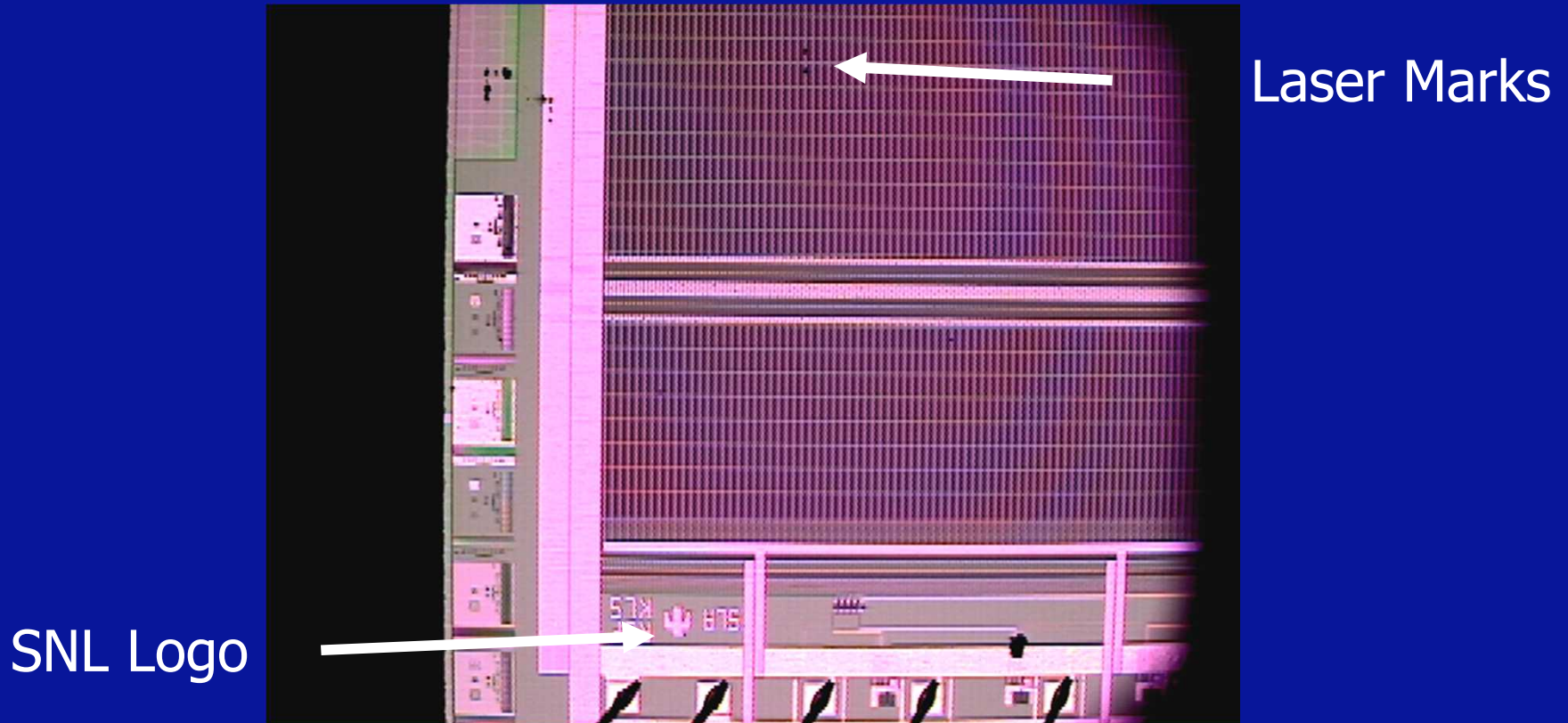


# Optical Image of Suspect Defect Location (2500X)

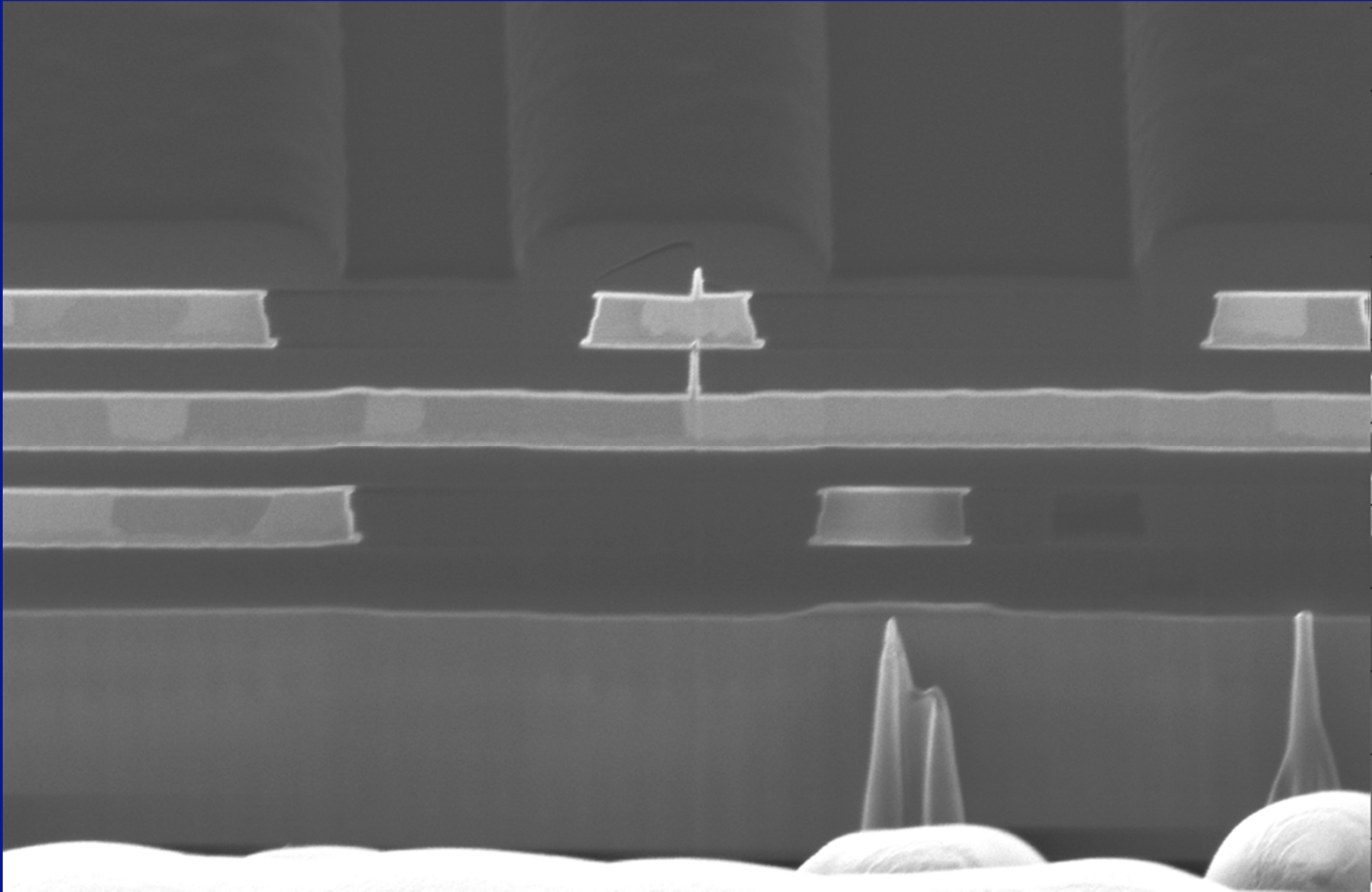




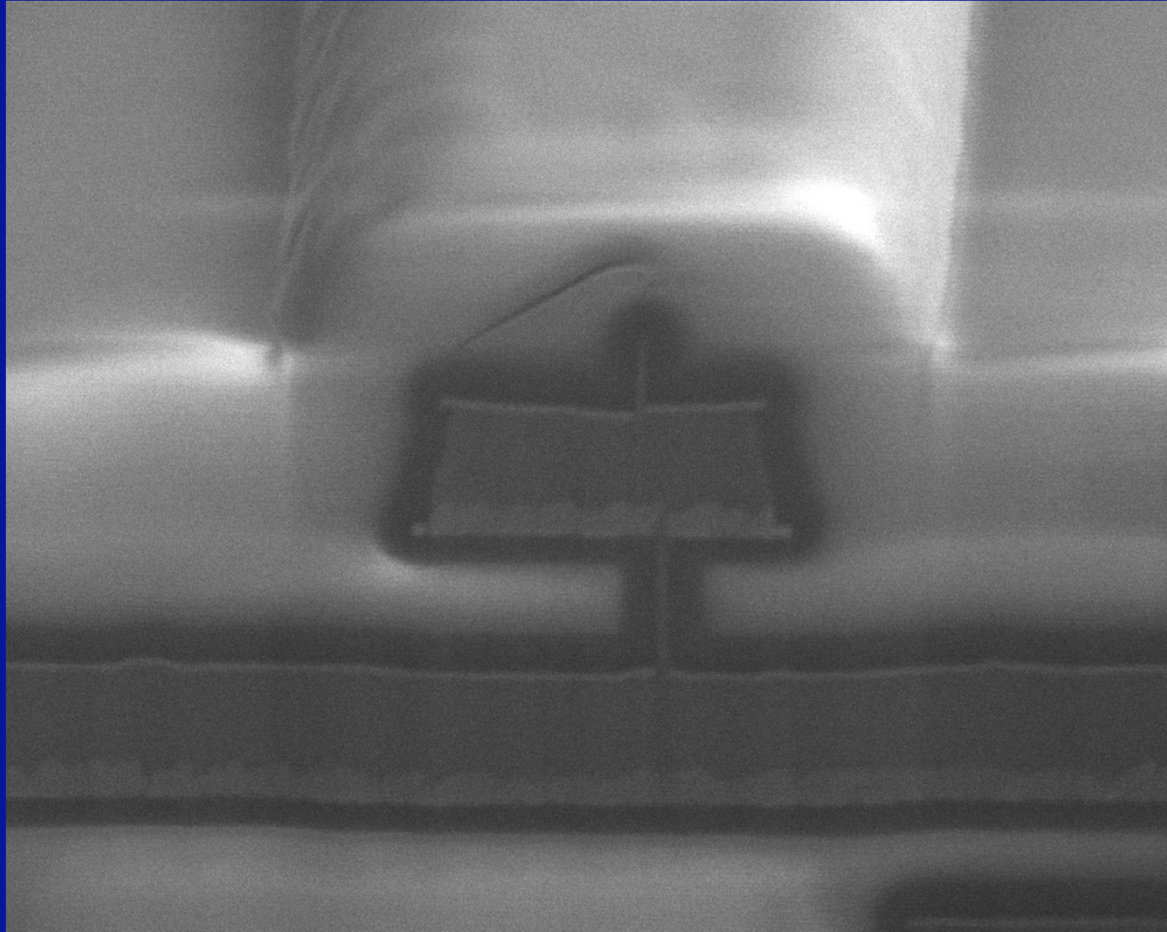
# Optical Image showing laser marks relative to die orientation



# FIB Image of Short on SN 1669



# Field Emission SEM Image of Short on SN1669





# Discussion

- **Cracking believed to have occurred during packaging**
- **9-day delay between metal-3 patterning and phosphosilicate glass deposition**
- **Moisture uptake in the dielectric layers believed to have put metal layers in compression, resulting in the extrusion**
- **Moisture believed to be responsible for cracking**